



## Additive Manufacturing: Technology, Challenges and Applications

Guest Editor:

**Dr. Santiago Ferrándiz-Bou**

Instituto Universitario de  
Investigación de Tecnología de  
los Materiales (IUITM), Universitat  
Politécnica de València (UPV),  
03801 Alcoy, Spain

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### Message from the Guest Editor

Dear Colleagues,

This Special Issue focuses on recent advances in additive manufacturing processes, applications and technologies. There is a growing need to know determine the new industrial applications of AM, and identify the new materials that are being applied in the field. It is necessary to discover what the future trends of new technologies are. Each technology and each application sector present needs that must be considered, from the part's design, to the processing conditions of the same. Original research papers and review articles are invited for this Special Issue.

Dr. Santiago Ferrandiz  
*Guest Editor*





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## Editor-in-Chief

### Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China  
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

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*Micromachines* Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

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